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Part Number: [0717640016](#)
Status: **Active**
Description: 2.54mm (.100") Pitch C-Grid® Breakaway Header, Low Profile, Dual Row, Right Angle, High Temperature, 16 Circuits, Tin (Sn) Plating

Documents:

| | |
|---|--|
| 3D Model | Product Specification PS-71764 (PDF) |
| Packaging Specification (PDF) | RoHS Certificate of Compliance (PDF) |
| Drawing (PDF) | |

Agency Certification

| | |
|-----|---------|
| CSA | LR19980 |
| UL | E29179 |

General

| | |
|----------------|-------------------------------|
| Product Family | PCB Headers |
| Series | 71764 |
| Application | Board-to-Board, Wire-to-Board |
| Product Name | C-Grid® |

Physical

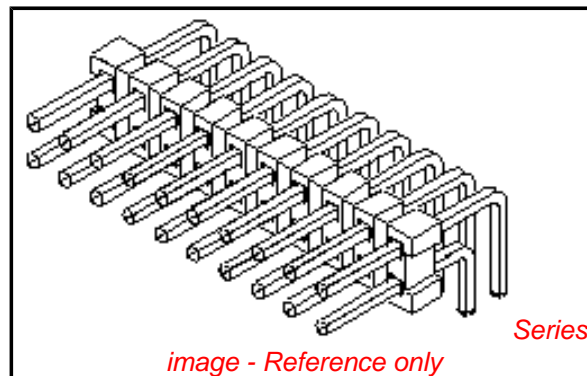
| | |
|--------------------------------|------------------------|
| Breakaway | Yes |
| Circuits (Loaded) | 16 |
| Circuits (maximum) | 16 |
| Durability (mating cycles max) | 25 |
| Flammability | 94V-0 |
| Glow-Wire Compliant | No |
| Lock to Mating Part | None |
| Material - Metal | Brass, Phosphor Bronze |
| Material - Plating Mating | Tin |
| Material - Plating Termination | Tin |
| Number of Rows | 2 |
| Orientation | Right Angle |
| PC Tail Length (in) | 0.110 In |
| PC Tail Length (mm) | 2.79 mm |
| PCB Locator | No |
| PCB Retention | None |
| Packaging Type | Tube |
| Pitch - Mating Interface (in) | 0.100 In |
| Pitch - Mating Interface (mm) | 2.54 mm |
| Plating min: Mating (µin) | 150 |
| Plating min: Mating (µm) | 3.75 |
| Plating min: Termination (µin) | 150 |
| Plating min: Termination (µm) | 3.75 |
| Polarized to Mating Part | No |
| Shrouded | No |
| Stackable | Yes |
| Temperature Range - Operating | -40°C to +105°C |
| Termination Interface: Style | Through Hole |

Electrical

| | |
|-------------------------------|------|
| Current - Maximum per Contact | 3A |
| Voltage - Maximum | 250V |

Solder Process Data

| | |
|------------------------------|------------------------------|
| Lead-free Process Capability | SMC & Wave Capable (TH only) |
| Process Temperature max. C | 260 |



EU RoHS

ELV and RoHS Compliant
REACH SVHC Contains SVHC: No
Halogen-Free Status
Halogen-Free

China RoHS



Need more information on product environmental compliance?

Email productcompliance@molex.com
 For a multiple part number RoHS Certificate of Compliance, [click here](#)

Please visit the [Contact Us](#) section for any non-product compliance questions.

Search Parts in this Series
[71764Series](#)

Material Info

Reference - Drawing Numbers

Product Specification

Sales Drawing

PS-71764

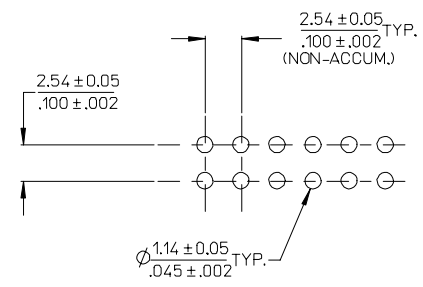
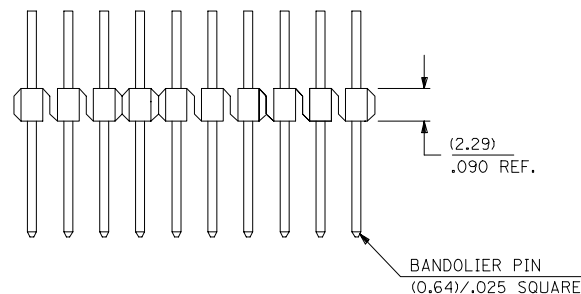
SD-71764-001

This document was generated on 03/31/2010

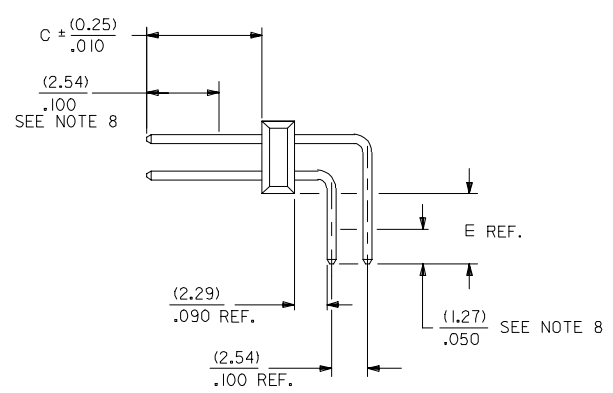
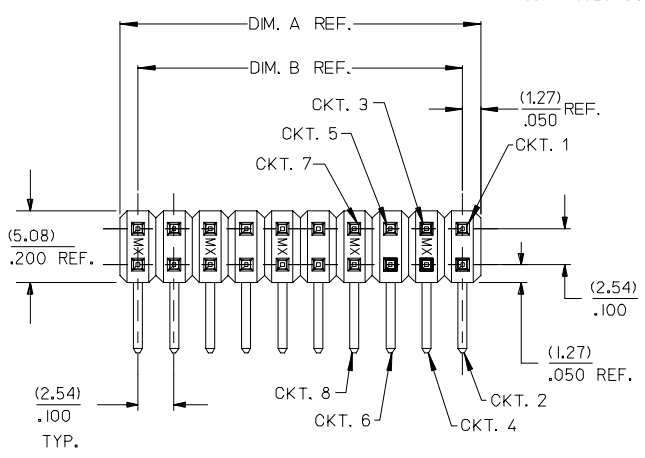
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13 12 11 10 9 8 7 6 5 4 3 2 1

| CKTS | DIM. A | DIM. B |
|------|---------------|---------------|
| 04 | (5.08)/.200 | (2.54)/.100 |
| 06 | (7.62)/.300 | (5.08)/.200 |
| 08 | (10.16)/.400 | (7.62)/.300 |
| 10 | (12.70)/.500 | (10.16)/.400 |
| 12 | (15.24)/.600 | (12.70)/.500 |
| 14 | (17.78)/.700 | (15.24)/.600 |
| 16 | (20.32)/.800 | (17.78)/.700 |
| 18 | (22.86)/.900 | (20.32)/.800 |
| 20 | (25.40)/1.000 | (22.86)/.900 |
| 22 | (27.94)/1.100 | (25.40)/1.000 |
| 24 | (30.48)/1.200 | (27.94)/1.100 |
| 26 | (33.02)/1.300 | (30.48)/1.200 |
| 28 | (35.56)/1.400 | (33.02)/1.300 |
| 30 | (38.10)/1.500 | (35.56)/1.400 |



RECOMMENDED P.C. BOARD HOLE LAYOUT



- NOTES:
- MATERIAL: WAFER - HIGH TEMPERATURE THERMAL PLASTIC, 94V-0; COLOR: BLACK
PIN - COPPER ALLOY
 - PLATING:
TIN - (0.00381)/.000150 MINIMUM TIN PLATE OVER NICKEL PLATE.
15 GOLD - (0.00038)/.000015 MINIMUM GOLD PLATE IN SELECT AREA.
(0.00191)/.000075 MINIMUM TIN PLATE IN SELECT AREA, OVER NICKEL PLATE OVERALL.
30 GOLD - (0.00076)/.000030 MINIMUM GOLD PLATE IN SELECT AREA.
(0.00191)/.000075 MINIMUM TIN PLATE IN SELECT AREA, OVER NICKEL PLATE OVERALL.
 - * THE PRIMARY SHIPPING CARTON WILL BE LABELED 'COMPLIANT TO RoHS DIRECTIVE 2002/95/EC AND ELV ANNEX II OF DIRECTIVE 2000/53/EC'. CARTONS WITHOUT THIS LABEL MAY CONTAIN PRODUCT WITH LEAD.
 - PRODUCT CONFORMS TO PS-71764.
 - PACKAGING INFORMATION:
FOR 4 THRU 8 CIRCUIT PARTS USE PK-70873-0353
FOR 10 CIRCUITS AND OVER USE PK-70873-0075
 - FOR ILLUSTRATION PURPOSES, 20 (DUAL 10) CIRCUIT SIZE IS SHOWN.
 - PINS MUST MEET SOLDERABILITY SPEC. ES-152, EXCEPT VOIDS ARE PERMISSIBLE AT BANDOLIER PIN AT BANDOLIER PIN FAYING SURFACE. (APPROX. (0.64)/.025 LNG X (0.15)/.006 WD. REF.) 2 LOCATIONS
 - WAFER TO BE FLAT WITHIN (0.03 MM/CM) OR .003 IN./IN
 - MEASURE POINT FOR PLATING THICKNESS.
 - THIS PART CONFORMS TO CLASS B REQUIREMENTS OF COSMETIC SPECIFICATION PS-45499-002

| | |
|------|------|
| 2 | A |
| 1 | A1 |
| SHT. | REV. |

| | | | | | | | | |
|--|---------------------|--|---|---|--|--------------|--|------------------------|
| ADD NOTE 9 EC NO: UCP2007-1441 DRAWN/PRD: 2006/12/11 CHKD: ADERR 2006/12/11 APPR: FSM TH 2006/12/12 A1 | QUALITY SYMBOLS | GENERAL TOLERANCES (UNLESS SPECIFIED) | | DIMENSION STYLE MM/IN | | SCALE 4:1 | DESIGN UNITS INCH | THIRD ANGLE PROJECTION |
| | | 4 PLACES ± --- ± --- 3 PLACES ± --- ± .01 2 PLACES ± 0.25 ± .01 1 PLACE ± 0.25 ± --- ANGULAR ±1/2° | mm INCH DRAWN BY CAC DATE 1995/08/23 CHECKED BY PR DATE 1995/08/23 APPROVED BY DJB DATE 1995/08/23 | TITLE DUAL ROW WAFER ASS'Y W/BREAK-OFF OPTION RT. ANG. (0.64)/.025 SQ PINS | | | MATERIAL NO. MOLEX INCORPORATED DOCUMENT NO. SD-71764-001 | |
| DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS | | SEE TABLE | | THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION | | | SHEET NO. 1 OF * | |

12 11 10 9 8 7 6 5 4 3 2 1

| ITEM NO: 71764-0004/0030, 9003 | | | ITEM NO: 71764-0104/0130, 9001, 9004 | | | ITEM NO: 71764-0204/0230, 9000, 9002 | | |
|--------------------------------|-------------|--------------------|--------------------------------------|-------------|--------------------|--------------------------------------|-------------|--------------------|
| DIM. C | | (6.10)/.240 | DIM. C | | (6.10)/.240 | DIM. C | | (6.10)/.240 |
| DIM. E (REF.) | | (2.79)/.110 | DIM. E (REF.) | | (2.79)/.110 | DIM. E (REF.) | | (2.79)/.110 |
| FINISH | | TIN | FINISH | | 15 GOLD | PLATING FINISH | | 30 GOLD |
| CONNECTOR END PLATING | | TIN | CONNECTOR END PLATING | | GOLD | CONNECTOR END PLATING | | GOLD |
| P.C. BOARD END PLATING | | TIN | P.C. BOARD END PLATING | | TIN | P.C. BOARD END PLATING | | TIN |
| PACKAGING | | SEE NOTE 4 SHEET 1 | PACKAGING | | SEE NOTE 4 SHEET 1 | PACKAGING | | SEE NOTE 4 SHEET 1 |
| CKTS | ITEM NUMBER | VOIDS | CKTS | ITEM NUMBER | VOIDS | CKTS | ITEM NUMBER | VOIDS |
| 04 | 71764-0004 | | 04 | 71764-0104 | | 04 | 71764-0204 | |
| 06 | 71764-0006 | | 06 | 71764-0106 | | 06 | 71764-0206 | |
| 08 | 71764-0008 | | 08 | 71764-0108 | | 08 | 71764-0208 | |
| 10 | 71764-0010 | | 10 | 71764-0110 | | 10 | 71764-0210 | |
| 12 | 71764-0012 | | 12 | 71764-0112 | | 12 | 71764-0212 | |
| 14 | 71764-0014 | | 14 | 71764-0114 | | 14 | 71764-0214 | |
| 16 | 71764-0016 | | 16 | 71764-0116 | | 16 | 71764-0216 | |
| 18 | 71764-0018 | | 18 | 71764-0118 | | 18 | 71764-0218 | |
| 20 | 71764-0020 | | 20 | 71764-0120 | | 20 | 71764-0220 | |
| 22 | 71764-0022 | | 22 | 71764-0122 | | 22 | 71764-0222 | |
| 24 | 71764-0024 | | 24 | 71764-0124 | | 24 | 71764-0224 | |
| 26 | 71764-0026 | | 26 | 71764-0126 | | 26 | 71764-0226 | |
| 28 | 71764-0028 | | 28 | 71764-0128 | | 28 | 71764-0228 | |
| 30 | 71764-0030 | | 30 | 71764-0130 | | 30 | 71764-0230 | |
| 06 | 71764-9003 | 3 | 06 | 71764-9001 | 3, 4 | 06 | 71764-9002 | 3, 4 |
| | | | 08 | 71764-9004 | 5, 6 | | | |
| | | | | | | 10 | 71764-9000 | 8 |

| | | | | | |
|---------------------|------|----------------------------|--------------|---|--------------|
| A | REV: | ECR/ECN INFORMATION | TITLE: | DUAL ROW WAFER ASS'Y W/ BREAK-OFF OPTION RT. ANG. (0.64)/.025 SQ PINS | SHEET No. |
| | | EC No: UCP2007-0449 | | | - 2 - |
| | | DATE: 2006-08-18 | | | |
| DOCUMENT NUMBER: | | CREATED / REVISED BY: | CHECKED BY: | APPROVED BY: | |
| SD-71764-001 | | PRIDDER | ADERR | FSMITH | |

